

**REMARKS**

Reconsideration and allowance of this application, as amended, is respectfully requested.

This amendment is in response to the Office Action dated September 16, 2005. Appreciation is expressed to Examiner Williams for his courtesy and helpfulness during the personal interview conducted in this matter on November 4, 2005. By the present amendment, the claims have been amended to conform with amendments discussed during the interview. The following remarks are intended to serve as a Statement of Summary of Interview regarding the interview.

By virtue of the present amendment, all of the claims in the present application have been canceled except for claims 91-101. In addition, independent claims 91 and 96 have each been amended to include a further feature from claim 39 in the related continuation application Serial No. 10/105,236 (which is a continuation application of the present application).

Reconsideration and allowance of the amended independent claims 91 and 96 and their respective dependent claims is respectfully requested. As noted above and as discussed during the interview, each of these claims has been amended to include the limitation:

"wherein a height of said bump electrodes is greater than a thickness of said resin sealing body from said second surface of said substrate in a thickness direction of said semiconductor pellet."

Referring to Figs. 2 and 3, this greater height for the bump electrodes 4 relative to the height of the resin 7A on the second surface of the substrate (i.e., the same

surface as the bump electrodes) is clearly defined by the amended independent claims 91 and 96. In the cited primary reference to Hinrichsmeyer (USP 4,996,587), on the other hand, there is clearly no corresponding structure for this as apparently recognized by the Examiner since the last Office Action in the continuation application Serial No. 10/105,236 did not reject dependent claim 39 in that case, which has the same limitation now found in independent claims 91 and 96 of the present application, over Hinrichsmeyer. As such, it is respectfully submitted, that on the record of the continuation application Serial No. 10/105,236, the subject matter of claim 39, which has been added to the present claims 91 and 96, is clearly patentable over the primary reference to Hinrichsmeyer.

With regard to the secondary reference to Kondo, this reference was cited in the present case with regard to its teachings concerning epoxy impregnated substrates. Although this is of general interest with regard to claim language directed to the substrate (specifically that the substrate is formed of a glass fiber impregnated with resin), nothing in the secondary reference to Kondo suggests modifying Hinrichsmeyer to provide the height limitation of the bump electrodes now defined in the amended independent claims 91 and 96. Accordingly, reconsideration and allowance of these amended independent claims 91 and 96, and their respective dependent claims, is respectfully requested.

With regard to the amendments made to claims 91 and 96, as noted above, these limitations can be read, for example, on Figs. 2 and 3 (as well as other Figures such as Figs. 10, 11 and 12) in terms of the bump electrodes having a greater height than the resin 7A on the second surface of the substrate. Referring to

Hinrichsmeyer, on the other hand, the solder balls 25 used in the Office Action to read on the claimed bump electrodes, clearly have much less height than the resin 28 formed on the same surface. Thus, the claim structure now defined by independent claims 91 and 96 in which the bump electrodes have a greater height than the resin which is formed on the same surface clearly distinguishes over the solder balls 25 taught by the Hinrichsmeyer reference. This distinction, which is also found in claim 39 in continuation application Serial No. 10/105,236, was apparently recognized in the continuation application by virtue of the fact that claim 39 was not rejected over Hinrichsmeyer. Therefore, allowance of this feature in the amended independent claims 91 and 96 is respectfully requested in the present case as well.

As also discussed during the interview, independent claims 91 and 96 each define that the first and second bump electrodes are arranged to overlap the semiconductor pellet in a plane view, respectively. One example of such an arrangement of the first and second bump electrodes both being arranged to overlap the semiconductor pellet can be seen in Fig. 13, where the first bump electrodes are on one side of the slit and the second bump electrodes are on the other side of the slit (with the semiconductor pellet being showed by the dashed lines and marked with the numeral 2). Clearly, this serves as another distinction over the Hinrichsmeyer arrangement, which is unsuggested by Kondo, since the elements 25 relied on in the Office Action to represent the claimed bump electrodes are clearly not formed to overlap the semiconductor pellet 19 in a plane view at all.

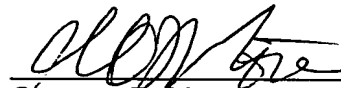
For the reasons set forth above, it is respectfully submitted that independent claims 91 and 96 are now in condition for allowance, together with their respective

dependent claims, and, accordingly, allowance of all of claims 91-101 is respectfully requested.

If the Examiner believes that there are any other points which may be clarified or otherwise disposed of either by telephone discussion or by personal interview, the Examiner is invited to contact Applicants' undersigned attorney at the number indicated below.

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**Antonelli, Terry, Stout & Kraus, LLP**



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